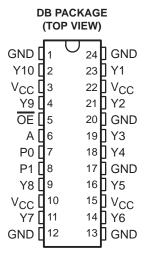
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- **Controlled Baseline** 
  - One Assembly/Test Site, One Fabrication
- **Extended Temperature Performance of** -55°C to 125°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree†
- Low Output Skew, Low Pulse Skew for **Clock-Distribution and Clock-Generation Applications**
- Operates at 3.3-V V<sub>CC</sub>
- **LVTTL-Compatible Inputs and Outputs**
- **Supports Mixed-Mode Signal Operation** (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- **Distributes One Clock Input to 10 Outputs**
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- **Outputs Have Internal Series Damping Resistor to Reduce Transmission Line**
- Distributed V<sub>CC</sub> and Ground Pins Reduce Switching Noise
- State-of-the-Art *EPIC-*II*B*™ BiCMOS Design Significantly Reduces Power Dissipation
- Shrink Small-Outline (DB) Package



### description

The CDC2351 is a high-performance clock-driver circuit that distributes one input (A) to 10 outputs (Y) with minimum skew for clock distribution. The output-enable  $(\overline{OE})$  input disables the outputs to a high-impedance state. Each output has an internal series damping resistor to improve signal integrity at the load. The CDC2351 operates at nominal 3.3-V V<sub>CC</sub>.

The propagation delays are adjusted at the factory using the P0 and P1 pins. The factory adjustments ensure that the part-to-part skew is minimized and is kept within a specified window. Pins P0 and P1 are not intended for customer use and should be connected to GND.

The CDC2351M is characterized for operation over the full military temperature range of -55°C to 125°C.

#### ORDERING INFORMATION

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
−55°C to 125°C	SSOP – DB Tape and Reel		CDC2351MDBREP	CK2351MEP

<sup>†</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

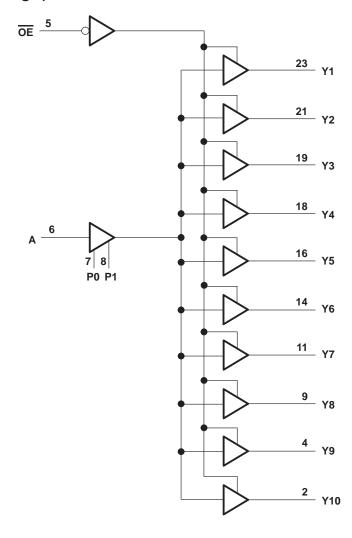
EPIC-IIB is a trademark of Texas Instruments.



#### **FUNCTION TABLE**

INP	UTS	OUTPUTS
Α	OE	In
L	Н	Z
Н	Н	Z
L	L	L
Н	L	Н

## logic diagram (positive logic)





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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	
Voltage range applied to any output in the high state or power-off state,	
V <sub>O</sub> (see Note 1)	
Current into any output in the low state, I <sub>O</sub>	24 mA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0)	
Output clamp current, I <sub>OK</sub> (V <sub>I</sub> < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}$ C (in still air) (see Note 2): DB package	
Storage temperature range, T <sub>sta</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		3	3.6	V
VIH	High-level input voltage		2		V
$V_{IL}$	Low-level input voltage			8.0	V
VI	Input voltage				V
ЮН	High-level output current			-12	mA
loL	Low-level output current			12	mA
fclock	Input clock frequency			100	MHz
TA	Operating free-air temperature	CDC2351M	-55	125	°C

NOTE 3: Unused pins (input or I/O) must be held high or low.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		MIN	TYP	MAX	UNIT		
VIK	V <sub>CC</sub> = 3 V,	I <sub>I</sub> = -18 mA				-1.2	V
Voн	V <sub>CC</sub> = 3 V,	I <sub>OH</sub> = – 12 mA		2			V
V <sub>OL</sub>	$V_{CC} = 3 V$ ,	I <sub>OL</sub> = 12 mA				0.8	V
lį	V <sub>CC</sub> = 3.6 V,	$V_I = V_{CC}$ or GND	V <sub>I</sub> = V <sub>CC</sub> or GND				μΑ
1 <sub>0</sub> ‡	V <sub>C</sub> C = 3.6 V,	V <sub>O</sub> = 2.5 V	-7		-70	mA	
loz	V <sub>C</sub> C = 3.6 V,	V <sub>CC</sub> = 3 V or 0				±10	μΑ
			Outputs high			0.3	
ICC	V <sub>CC</sub> = 3.6 V,	$I_O = 0$ , $V_I = V_{CC}$ or GND	Outputs low			15	mA
			Outputs disabled			0.3	
C <sub>i</sub>	$V_I = V_{CC}$ or GND,	V <sub>CC</sub> = 3.3 V,	f = 10 MHz		4		pF
Co	$V_O = V_{CC}$ or GND,	V <sub>CC</sub> = 3.3 V,	f = 10 MHz		6		рF

<sup>‡</sup> Not more than one output should be tested at a time and the duration of the test should not exceed one second.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, see the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

## **CDC2351-EP** 1-LINE TO 10-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS

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## switching characteristics, C<sub>L</sub> = 50 pF (see Figure 1 and Figure 2)

PARAMETER	FROM			C = 3.3 \ A = 25°C	V,	V <sub>CC</sub> = 3 V T <sub>A</sub> = -55°C	UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub>	۸	Y	3.8	4.3	4.8	1.1	11	20
<sup>t</sup> PHL	А	ľ	3.6	4.1	4.6	1	9.7	ns
<sup>t</sup> PZH	<u>O</u>	V	2.4	4.9	6	1	12	
t <sub>PZL</sub>	OE	Y	2.4	4.3	6	1	11.1	ns
<sup>t</sup> PHZ	<u>OE</u>	V	2.2	4.4	6.3	1	11.1	
<sup>t</sup> PLZ	OE	Y	2.2	4.6	6.3	1	11.5	ns
tsk(o)	А	Υ		0.3	0.5		2.5	ns
<sup>t</sup> sk(p)	А	Υ		0.2	0.8		3	ns
<sup>t</sup> sk(pr)	А	Υ			1			ns
t <sub>r</sub>	А	Υ					2.5	ns
t <sub>f</sub>	А	Υ					2.5	ns

# switching characteristics temperature and $V_{\hbox{\footnotesize{CC}}}$ coefficients over recommended operating free-air temperature and $V_{\hbox{\footnotesize{CC}}}$ range (see Note 4)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN MAX	UNIT
∝t <sub>PLH</sub> (T)	Average temperature coefficient of low-to-high propagation delay	Α	Υ	85†	ps/10°C
∞tpHL(T)	Average temperature coefficient of high-to-low propagation delay	Α	Υ	<sub>50</sub> †	ps/10°C
∝tPLH(VCC)	Average V <sub>CC</sub> coefficient of low-to-high propagation delay	А	Υ	-145‡	ps/ 100 mV
∝t <sub>PHL</sub> (V <sub>CC</sub> )	Average V <sub>CC</sub> coefficient of high-to-low propagation delay	А	Υ	-100‡	ps/ 100 mV

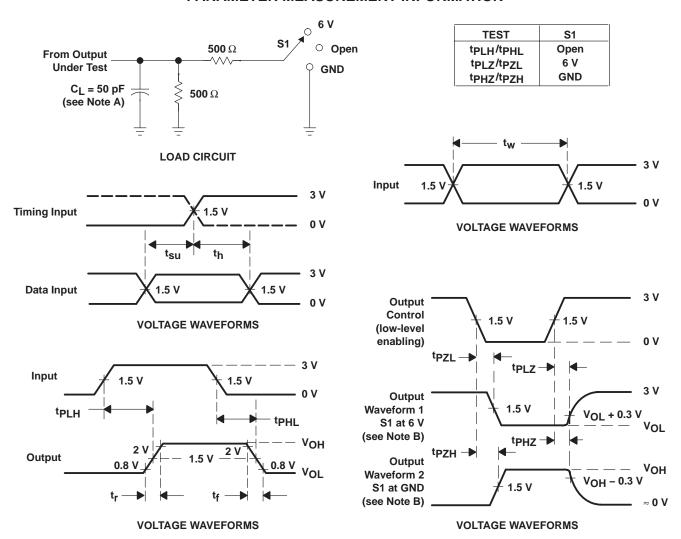
<sup>† ∝</sup>tpLH(T) and ∝tpHL(T) are virtually independent of VCC.

‡ ctpLH(V<sub>CC</sub>) and ctpHL(V<sub>CC</sub>) are virtually independent of temperature.

NOTE 4: This data was extracted from characterization material and has not been tested at the factory.



#### PARAMETER MEASUREMENT INFORMATION

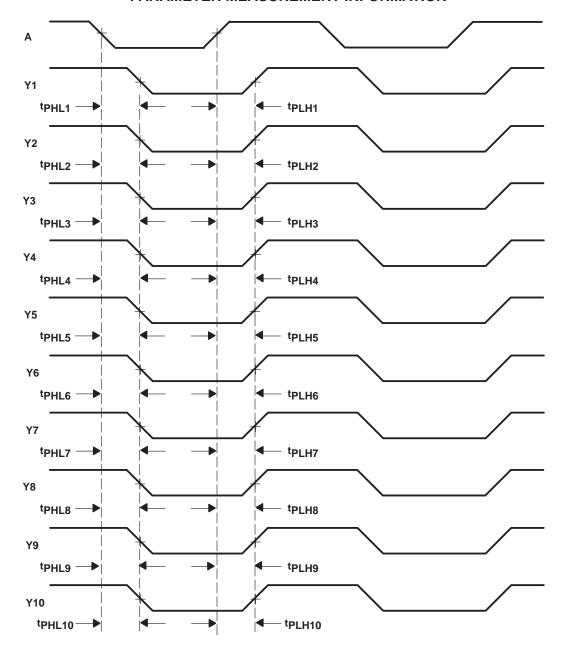


NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Output skew, t<sub>sk(o)</sub>, is calculated as the greater of:

   The difference between the fastest and slowest of t<sub>PLHn</sub> (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)
  - The difference between the fastest and slowest of tpHLn (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)
  - B. Pulse skew,  $t_{sk(p)}$ , is calculated as the greater of  $|t_{PLHn} t_{PHLn}|$  (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10).

  - C. Process skew, t<sub>Sk(pr)</sub>, is calculated as the greater of:

     The difference between the fastest and slowest of t<sub>PLHn</sub> (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical
    - The difference between the fastest and slowest of tpHLn (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical operating conditions.

Figure 2. Waveforms for Calculation of  $t_{sk(0)}$ ,  $t_{sk(p)}$ ,  $t_{sk(pr)}$ 





## PACKAGE OPTION ADDENDUM

10-Dec-2020

#### PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CDC2351MDBREP	ACTIVE	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	CK2351MEP	Samples
V62/04757-01XE	ACTIVE	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-55 to 125	CK2351MEP	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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## **PACKAGE OPTION ADDENDUM**

10-Dec-2020

#### OTHER QUALIFIED VERSIONS OF CDC2351-EP:

• Automotive: CDC2351-Q1

NOTE: Qualified Version Definitions:

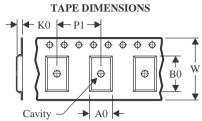
- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 3-Jun-2022

## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

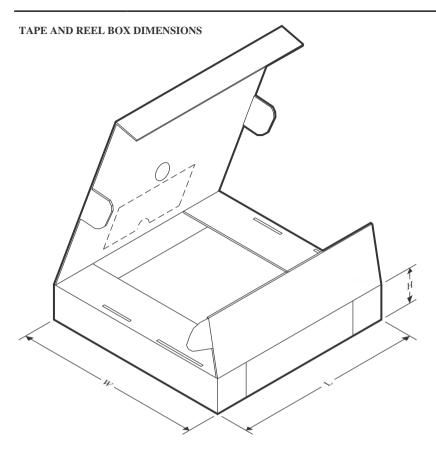


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC2351MDBREP	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 3-Jun-2022



### \*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	CDC2351MDBREP	SSOP	DB	24	2000	356.0	356.0	35.0

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